



Product/Process Change Notice - PCN 12_0225 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: ADMP504 ASIC Die Revision

Publication Date: 31-Aug-2012

Effectivity Date: 29-Nov-2012 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

A minor ASIC design change involving the metal layer only to re-center sensitivity at the -38 dB V target.

Reason For Change

The ASIC design change results in a tighter distribution around the targeted sensitivity (-38 dBV).

Impact of the change (positive or negative) on fit, form, function & reliability

No change to the form, fit, or function.

Summary of Supporting Information

Qualification will be performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Plan Summary.

Supporting Documents

Attachment 1: Type: Qualification Plan Summary

ADI_PCN_12_0225_Rev_-_Qual Plan.docx

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Added Parts On This Revision - Product Family / Model Number (2)				
ADMP504 / ADMP504ACEZ-RL	ADMP504 / ADMP504ACEZ-RL7			

Appendix B - Revision History			
Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	31-Aug-2012	29-Nov-2012	Initial Release

Analog Devices, Inc.

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